Fabrication of Si Nanotube Arrays by Nanoimprint Lithography with Spacer Patterning International Center for Materials Nanoarchitectonics (MANA), National Institute for Materials

Science (NIMS)¹

°Yonglie Sun¹, Wipakorn Jevasuwan¹, Naoki Fukata¹

E-mail: SUN.Yonglie@nims.go.jp

Introduction

Top-down approaches provide vertical 1D structure with smooth surface, high crystal quality, and highly ordered arrangement, which make them suitable for electronic applications. Lithography, and self-assembled nanosphere bead templates have more recently been developed to fabricate Si nanotubes (SiNTs), but they require a manufacturing complex process, long processing time, or use of noble metals. On the other side, spacer patterning is known as one of the techniques used to overcome the resolution limit in the semiconductor industry [1].

Here, we propose the use of nanoimprint lithography (NIL) and spacer patterning technique atomic layer deposition (ALD) to fabricate SiNTs with high aspect ratio and nano-scale wall thickness.

Experimental section

The fabrication process to fabricate vertical Si NT arrays is shown in Figure 1a. Si(100) substrates were patterned by a photoresist nanohole array by UV-NIL. Then, an Al₂O₃ layer is uniformly deposited over the photoresist by ALD. Trimethylaluminum (TMA) and deionized water were used as precursors and the thickness of Al₂O₃ was controlled by the number of ALD cycles. Next, the ring-like array pattern was achieved using inductively coupled plasma reactive ion etching (ICP-RIE) with CF₄ and Ar gases. To fabricate nanotube structures with high aspect ratio, SF₆ plasma followed by C₄F₈ plasma (Bosch process) was applied. The height of SiNTs was controlled by the number of Bosch cycles. Finally, the remaining Al₂O₃ was removed in HF.

Results and discussion

Figure 2 shows the reflectance spectra of Si NT arrays. Si NT arrays show a reduced reflection compared to Si nanowire arrays,

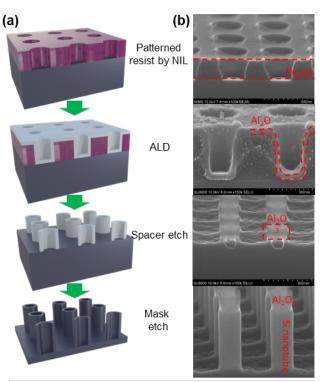
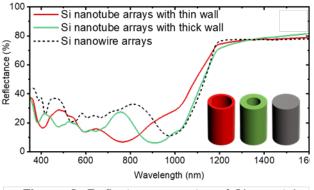
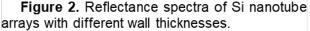


Figure 1. (a) Schematic illustration of the fabrication procedure for Si nanotube arrays using nanoimprint lithography (NIL) with spacer patterning. (b) Corresponding 30°-tilted SEM images.





demonstrating the enhanced light absorption effect of NTs. Si NT arrays with a larger diameter or a longer length seem to have an overall reduction in reflectance for 350–1100 nm.

[1] E. J. Nowak et al., IEEE Circuits Devices Mag., vol. 20, no. 1, pp. 20-31, Jan. 2004